

Electronic Acknowledgement Receipt

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Application Number:	10500381
Confirmation Number:	9028
Title of Invention:	Soi wafer manufacturing method and soi wafer
First Named Inventor:	Masatake Nakano
Customer Number:	25944
Filer:	Christopher W. Brown/Jori Krischke
Filer Authorized By:	Christopher W. Brown
Attorney Docket Number:	120164
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International Application Number:	

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		120164AAFR6-13-06.pdf	371740	yes	10

	Multipart Description		
	Doc Desc	Start	End
	Amendment After Final	1	1
	Claims	2	4
	Applicant Arguments/Remarks Made in an Amendment	5	10

Warnings:

Information:

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.